Components marked 'DNP' should not be populated.

Assembly variant: [No Variations]

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01351</th>
<th>REV: E1</th>
<th>SUN REV: Not In Version Control</th>
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</thead>
<tbody>
<tr>
<td>M5 Assembly Top</td>
<td>TID #: TIDA-01351</td>
<td></td>
<td></td>
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<tr>
<td>PLOT NAME = Top Assembly Drawing</td>
<td>GENERATED : 12/7/2016 2:29:44 PM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
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